



# Product Change Notification

**Change Notification #:** 118456 - 00  
**Change Title:** PROC ASIC ACC100 (Mount Bryce), JJACC100, PCN 118456-00, Product Design, Product Material, Alternate Substrate Supplier  
**Date of Publication:** August 25, 2021

## Key Characteristics of the Change:

Product Design, Product Material

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	November 29, 2021
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Note 1: J-STD-046, section 3.2.3.1b, stipulates that lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.

## Description of Change to the Customer:

In accordance with the ePG-PCN-2128-01 document attached, the products listed in the Products Affected / Intel Ordering Codes table below will undergo the following changes:

<b>Affected Processes/Products:</b>	Substrate for Mt Bryce device (PNC 30063)
<b>Description of Change(s):</b>	<ol style="list-style-type: none"><li>1. To use Semco as alternative substrate supplier, in addition to existing supplier Nanya.</li><li>2. Change PTH (CORE) via pad/drill sizes from 200/100um to 210/105um.</li><li>3. Change Blind and Buried (microvia) via drill size from 60um to 57um.</li></ol>
<b>Reason/Justification:</b>	<ol style="list-style-type: none"><li>1. Due to worldwide substrate supply constraints, it's necessary to move Mt Bryce substrate manufacturing to alternative supplier Semco for gaining required capacity.</li><li>2. There is no change on substrate materials from the existing substrate used (from Nanya). But there will be minor design changes as shown in "Description of Change(s)" 2 and 3. The changes are to accommodate Semco's manufacturing specifications. The electrical analysis results (insertion/return loss, XTalk and power integrity) show that the device still meets MGIO 16Bbps and DDR4 2666MT/s design requirements (see attached document).</li></ol> <div data-bbox="570 1472 646 1530" data-label="Image"></div>

## Customer Impact of Change and Recommended Action:

<u>Impact</u>	<u>Risk Description</u>	<u>Risk Mitigation</u>
Form <input type="checkbox"/>		
Fit <input type="checkbox"/>		
Function <input checked="" type="checkbox"/>	Changes on PTH via pad/drill sizes and microvia drill size may impact electrical performance.	Electrical analysis has been performed (in inserted report). The result shows low risk for the change.
Quality <input type="checkbox"/>		
Reliability <input checked="" type="checkbox"/>	Semco is a new supplier for ePG products. Product reliability needs to be assessed for device using Semco's substrate.	To perform package qual for Semco substrate. Target completion: end of Nov '21.
Resources <input type="checkbox"/>		
Others <input type="checkbox"/>		
No impact <input type="checkbox"/>	Not applicable	Not applicable

Please acknowledge receipt of this notification by completing the Customer Response section and returning a signed copy (**enclosed document ePG-PCN-2128-01**) to Sales or Customer Service within 30 days of the notification date (PCN date). PCN is deemed acknowledged/accepted if no response received.

For product support, please contact Sales or Customer Service in your region.

## Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	S-Spec	MM#
PROC ASIC ACC100	JJACC100	S RKQD	99AD92

## PCN Revision History:

**Date of Revision:**

August 25, 2021

**Revision Number:**

00

**Reason:**

Originally Published PCN



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## 118456 - 00

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific/PRC Contact:** [apagccb@intel.com](mailto:apagccb@intel.com)

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